

	L #	Hits	Search Text	DBs	Time Stamp
1	L1	13	("3562005" "3647450" "3904783" "4304849" "4347304").PN.	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/02/27 11:43
2	L2	8	((("5834844") or ("5902472") or ("6281567") or ("5736780") or ("6281567"))).PN.	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/02/27 11:48
3	L3	3385	(427/553,554,555,558,581,586,595,597).CCLS.	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/02/27 11:49
4	L4	4323	(427/421,422,424,425,426,427).CCLS.	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/02/27 11:51
5	L5	11131	(Uv ultraviolet ultra adj violet) same ((solution liquid complex solvent cyanide)with (metal\$4 organometal\$4 "Au.m/c." gold Cu copper "Pd.m/c." palladium "Ni.m/c." nickel))	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/02/27 12:09
6	L6	3880	(Uv ultraviolet ultra adj violet) same ((chelate carboxylate dithiooxalate amine EDTA ethylenediamine acetate "CN.u/c.")with (metal\$4 organometal\$4 "Au.m/c." gold Cu copper "Pd.m/c." palladium "Ni.m/c."	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/02/27 12:07

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3

	L #	Hits	Search Text	DBs	Time Stamp
7	L7	1591	6 same (solution liquid complex solvent disolv\$5 dispersion)	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/02/27 12:09
8	L8	11099	5 same (solution liquid complex solvent disolv\$5 dispersion)	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/02/27 12:09
9	L9	91	(Uv ultraviolet ultra adj violet) same ((solution liquid complex solvent disolv\$5 dispersion)with ("KAu(CN).sub.2" or organo adj metal\$4 or metal adj organic))	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/02/27 12:11
10	L10	11404	7 or 8 or 9	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/02/27 12:11
11	L11	166	10 and 3	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/02/27 12:12
12	L12	87	11 and (4 or spray\$5 or ink adj jet or direct adj writ\$5)	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/02/27 12:14

4

13	L13	14	11 and (ink adj jet)	US - PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/02/27 12:15
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	L #	Hits	Search Text	DBs	Time Stamp
14	L14	23	12 and (gold "Au.m/c." "KAu(CN).sub.2") not 13	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/02/27 12:17
15	L15	6	13 and (gold "Au.m/c." "KAu(CN).sub.2")	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/02/27 12:18
16	L16	8	13 not 15	US- PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/02/27 12:18

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Inventor Name Search Result

Your Search was:

Last Name = MURAYAMA

First Name = KEI

for 10/708,957

The Bib section in e-dan does NOT list
all relevant cases of

Application#	Patent#	Status	Date Filed	Title	Inventor Name
08698624	5777386	150	08/16/1996 ✓	SEMICONDUCTOR DEVICE AND MOUNT STRUCTURE THEREOF	MURAYAMA, KEI
08744994	5736780	150	11/07/1996	SEMICONDUCTOR DEVICE HAVING CIRCUIT PATTERN ALONG OUTER PERIPHERY OF SEALING RESIN AND RELATED PROCESSES	MURAYAMA, KEI
09262057	6281592	150	03/04/1999 X	PACKAGE STRUCTURE FOR SEMICONDUCTOR CHIP	MURAYAMA, KEI
09285971	6081038	150	04/05/1999 X	SEMICONDUCTOR CHIP PACKAGE STRUCTURE	MURAYAMA, KEI
09333515	6281567	150	06/15/1999	SUBSTRATE FOR MOUNTING SEMICONDUCTOR CHIP WITH PARALLEL CONDUCTIVE LINES	MURAYAMA, KEI
09333662	6312551	150	06/16/1999 X	METHOD FOR MOUNTING SEMICONDUCTOR CHIP ONTO CIRCUIT BOARD	MURAYAMA, KEI
09376606	6303998	150	08/18/1999 X	A SEMICONDUCTOR DEVICE HAVING A CHIP MOUNTED ON A RECTANGULAR SUBSTRATE	MURAYAMA, KEI
09414503	6344695	150	10/08/1999 ✓	SEMICONDUCTOR DEVICE TO BE MOUNTED ON MAIN CIRCUIT BOARD AND PROCESS FOR MANUFACTURING SAME DEVICE	MURAYAMA, KEI
09591785	6420787	150	06/12/2000 ✓	SEMICONDUCTOR DEVICE AND PROCESS OF PRODUCING SAME	MURAYAMA, KEI

09627976	6404070	150	07/28/2000	SEMICONDUCTOR DEVICE	MURAYAMA, KEI
09639262	Not Issued	161 <i>abd</i>	08/15/2000	SEMICONDUCTOR DEVICE AND PRODUCTION THEREOF	MURAYAMA, KEI
09645299	6738504	150	08/24/2000 X	INSPECTION APPARATUS FOR SEMICONDUCTOR DEVICE AND PARTS MOUNTER USING SAME	MURAYAMA, KEI
09734855	Not Issued	161	12/11/2000	SEMICONDUCTOR DEVICE AND PRODUCTION METHOD THEREOF	MURAYAMA, KEI
09734863	Not Issued	061	12/12/2000 X	BUMP INSPECTION APPARATUS AND METHOD	MURAYAMA, KEI
09760396	6713863	150	01/12/2001 X	SEMICONDUCTOR DEVICE HAVING A CARBON FIBER REINFORCED RESIN AS A HEAT RADIATION PLATE HAVING A CONCAVE PORTION	MURAYAMA, KEI
09767432	Not Issued	161	01/23/2001	HEAT RADIATION FIN USING A CARBON FIBER REINFORCED RESIN AS HEAT RADIATION PLATES STANDING ON A SUBSTRATE	MURAYAMA, KEI
09881004	6522719	150	06/14/2001 X	METHOD AND APPARATUS FOR MEASURING A BUMP ON A SUBSTRATE	MURAYAMA, KEI
09973111	6538332	150	10/09/2001 /	SEMICONDUCTOR DEVICE AND METHOD OF PRODUCTION OF SAME	MURAYAMA, KEI
09996643	6522022	150	11/27/2001 X	MOUNTING STRUCTURE FOR SEMICONDUCTOR DEVICES	MURAYAMA, KEI
10013398	6548326	150	12/13/2001 /	SEMICONDUCTOR DEVICE AND PROCESS OF PRODUCING SAME	MURAYAMA, KEI
10043943	Not Issued	161	01/11/2002	HEAT RADIATION FIN USING A CARBON FIBER REINFORCED RESIN AS HEAT RADIATION PLATES STANDING ON A SUBSTRATE	MURAYAMA, KEI
10114518	Not Issued	161	04/02/2002	SEMICONDUCTOR ELEMENT, CONNECTION	MURAYAMA, KEI

				STRUCTURE THEREOF, SEMICONDUCTOR DEVICE USING A PLURALITY OF SUCH ELEMENTS AND PROCESSES FOR MAKING THE SAME	
<u>10123211</u>	<u>6803664</u>	150	04/17/2002 X	SEMICONDUCTOR PACKAGE	MURAYAMA, KEI
<u>10270823</u>	<u>6797603</u>	150	10/15/2002 /	SEMICONDUCTOR DEVICE AND METHOD OF PRODUCTION OF SAME	MURAYAMA, KEI
<u>10335689</u>	<u>6861284</u>	150	01/02/2003 /	SEMICONDUCTOR DEVICE AND PRODUCTION METHOD THEREOF	MURAYAMA, KEI
<u>10603769</u>	Not Issued	030	06/26/2003 f	SEMICONDUCTOR CHIP MOUNTING APPARATUS AND MOUNTING METHOD	MURAYAMA, KEI
<u>10603812</u>	<u>6835597</u>	150	06/26/2003 X	SEMICONDUCTOR PACKAGE	MURAYAMA, KEI
<u>10704156</u>	Not Issued	041	11/10/2003 X	ELECTRONIC PARTS PACKAGING STRUCTURE AND METHOD OF MANUFACTURING THE SAME	MURAYAMA, KEI
<u>10708957</u>	Not Issued	071	04/02/2004	PATTERNING APPARATUS AND FILM PATTERNING METHOD	MURAYAMA, KEI
<u>10709096</u>	Not Issued	030	04/13/2004	WIRING SUBSTRATE AND ELECTRONIC PARTS PACKAGING STRUCTURE	MURAYAMA, KEI
<u>10709138</u>	Not Issued	030	04/15/2004	ELECTROLESS PLATING METHOD	MURAYAMA, KEI
<u>10709858</u>	Not Issued	030	06/02/2004 X	ELECTRONIC PARTS PACKAGING STRUCTURE AND METHOD OF MANUFACTURING THE SAME	MURAYAMA, KEI
<u>10717591</u>	Not Issued	030	11/21/2003 X	ELECTRONIC PARTS PACKAGING STRUCTURE AND METHOD OF MANUFACTURING THE SAME	MURAYAMA, KEI
<u>10720514</u>	Not Issued	092	11/25/2003 X	ELECTRONIC PARTS PACKAGING STRUCTURE HAVING MUTUALLY CONNECTED ELECTRONIC	MURAYAMA, KEI

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				PARTS THAT ARE BURIED IN A INSULATING FILM	
<u>10750905</u>	<u>6831000</u>	150	01/05/2004 X	SEMICONDUCTOR DEVICE MANUFACTURING METHOD	MURAYAMA, KEI
<u>10756763</u>	Not Issued	030	01/14/2004 A	ELECTRONIC PARTS PACKAGING STRUCTURE AND METHOD OF MANUFACTURING THE SAME	MURAYAMA, KEI
<u>10771506</u>	Not Issued	041	02/05/2004 A	ELECTRONIC PARTS PACKAGING STRUCTURE AND METHOD OF MANUFACTURING THE SAME	MURAYAMA, KEI
<u>10777232</u>	<u>6864120</u>	150	02/12/2004 A	SEMICONDUCTOR DEVICE HAVING A CARBON-FIBER REINFORCED RESIN AS A HEAT RADIATION PLATE HAVING A CONCAVE PORTION	MURAYAMA, KEI
<u>10781416</u>	Not Issued	030	02/18/2004 A	SEMICONDUCTOR DEVICE FABRICATION METHOD	MURAYAMA, KEI
<u>10794343</u>	Not Issued	030	03/05/2004 X	SEMICONDUCTOR DEVICE	MURAYAMA, KEI
<u>10796004</u>	Not Issued	020	03/10/2004 A	METHOD OF PRODUCTION OF MULTILAYER CIRCUIT BOARD WITH BUILT-IN SEMICONDUCTOR CHIP	MURAYAMA, KEI
<u>10826034</u>	Not Issued	030	04/16/2004 A	METHOD FOR MANUFACTURING SEMICONDUCTOR PACKAGE	MURAYAMA, KEI
<u>10851191</u>	Not Issued	030	05/24/2004 A	METHOD FOR THINNING WAFER BY GRINDING	MURAYAMA, KEI
<u>10852063</u>	Not Issued	030	05/24/2004 A	SEMICONDUCTOR DEVICE AND PRODUCTION METHOD THEREOF	MURAYAMA, KEI
<u>10901051</u>	Not Issued	030	07/29/2004 ?	INKJET PRINTER all apparatus	MURAYAMA, KEI
<u>10904087</u>	Not Issued	030	10/22/2004 A	ELECTRONIC PARTS PACKAGING STRUCTURE AND METHOD OF MANUFACTURING THE SAME	MURAYAMA, KEI
<u>10980162</u>	Not	020	11/04/2004	ELECTRICAL	MURAYAMA, KEI

A

	Issued			CHARACTERISTIC MEASURING PROBE AND METHOD OF MANUFACTURING THE SAME	
<i>child</i> <u>11011051</u> <i>all apparatus chains</i>	Not Issued	020	12/15/2004	PATTERNING APPARATUS AND FILM PATTERNING METHOD	MURAYAMA, KEI
<u>08162911</u>	Not Issued	166	12/08/1993 <i>X</i>	CANCER-RELATED PHARMACEUTICAL COMPOSITION	MURAYAMA, KEIICHI
<u>08432005</u>	5561050	250	05/01/1995	METHODS FOR DIAGNOSIS OF COLON, STOMACH AND PANCREATIC CANCER USING ANTIBODIES SPECIFIC FOR A MUCIN- TYPE CARBOHYDRATE CHAIN	MURAYAMA, KEIICHI

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MURAYAMA	KEI

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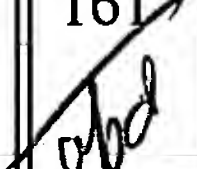
Time: 11:15:24

Inventor Name Search Result

Your Search was:

Last Name = HIGASHI

First Name = MITSUTOSHI

Application#	Patent#	Status	Date Filed	Title	Inventor Name
08227354	Not Issued	161 	04/13/1994	SEMICONDUCTOR DEVICE HAVING MOUNTING TERMINALS	HIGASHI, MITSUTOSHI
08502811	5732465	150	07/14/1995 X	METHOD OF MANUFACTURING ONE SIDE RESIN SEALING TYPE SEMICONDUCTOR DEVICES	HIGASHI, MITSUTOSHI
08620290	5834844	150	03/22/1996	SEMICONDUCTOR DEVICE HAVING AN ELEMENT WITH CIRCUIT PATTERN THEREON	HIGASHI, MITSUTOSHI
08698624	5777386	150	08/16/1996 X	SEMICONDUCTOR DEVICE AND MOUNT STRUCTURE THEREOF	HIGASHI, MITSUTOSHI
08895145	5918113	150	07/16/1997 X	PROCESS FOR PRODUCING A SEMICONDUCTOR DEVICE USING ANISOTROPIC CONDUCTIVE ADHESIVE	HIGASHI, MITSUTOSHI
08909594	6147311	150	08/12/1997 X	MULTI-LAYER CIRCUIT BOARD USING ANISOTROPIC ELECTROCONDUCTIVE ADHESIVE LAYER AND METHOD FOR PRODUCING SAME	HIGASHI, MITSUTOSHI
08930514	5902472	150	09/30/1997	AQUEOUS SOLUTION FOR FORMING METALLIC COMPLEX TIN-SILVER ALLOY PLATING SOLUTION AND METHOD OF PLATING WITH SAID PLATING SOLUTION	HIGASHI, MITSUTOSHI
08960336	5918746	150	10/29/1997 X	CARRIER FRAME USED FOR CIRCUIT BOARDS	HIGASHI, MITSUTOSHI
09040370	5960308	150	03/18/1998 X	PROCESS FOR MAKING A	HIGASHI,

				CHIP SIZED SEMICONDUCTOR DEVICE	mitsutoshi
09333515	6281567	150	06/15/1999	SUBSTRATE FOR MOUNTING SEMICONDUCTOR CHIP WITH PARALLEL CONDUCTIVE LINES	HIGASHI, mitsutoshi
09333662	6312551	150	06/16/1999 A	METHOD FOR MOUNTING SEMICONDUCTOR CHIP ONTO CIRCUIT BOARD	HIGASHI, mitsutoshi
09422850	6586845	150	10/25/1999 A	SEMICONDUCTOR DEVICE MODULE HAVING HEAT SPREADER ENGAGING A MOUNTING BOARD	HIGASHI, mitsutoshi
09430189	Not Issued	161	10/29/1999	SEMICONDUCTOR DEVICE HAVING EXTERNAL CONNECTING TERMINALS AND PROCESS FOR MANUFACTURING THE DEVICE	HIGASHI, mitsutoshi
09591785	6420787	150	06/12/2000 X	SEMICONDUCTOR DEVICE AND PROCESS OF PRODUCING SAME	HIGASHI, mitsutoshi
09627976	6404070	150	07/28/2000 X	SEMICONDUCTOR DEVICE	HIGASHI, mitsutoshi
09639262	Not Issued	161	08/15/2000	SEMICONDUCTOR DEVICE AND PRODUCTION THEREOF	HIGASHI, mitsutoshi
09645299	6738504	150	08/24/2000 A	INSPECTION APPARATUS FOR SEMICONDUCTOR DEVICE AND PARTS MOUNTER USING SAME	HIGASHI, mitsutoshi
09669728	6331679	150	09/26/2000 A	MULTI-LAYER CIRCUIT BOARD USING ANISOTROPIC ELECTRO-CONDUCTIVE ADHESIVE LAYER	HIGASHI, mitsutoshi
09669729	6544428	150	09/26/2000 A	METHOD FOR PRODUCING A MULTI-LAYER CIRCUIT BOARD USING ANISOTROPIC ELECTRO-CONDUCTIVE ADHESIVE LAYER	HIGASHI, mitsutoshi
09734855	Not Issued	161	12/11/2000	SEMICONDUCTOR DEVICE AND PRODUCTION METHOD THEREOF	HIGASHI, mitsutoshi
09734863	Not Issued	061	12/12/2000 X	BUMP INSPECTION APPARATUS AND METHOD	HIGASHI, mitsutoshi
09760396	6713863	150	01/12/2001	SEMICONDUCTOR DEVICE HAVING A CARBON FIBER	HIGASHI, mitsutoshi

				REINFORCED RESIN AS A HEAT RADIATION PLATE HAVING A CONCAVE PORTION	
09767432	Not Issued	161	01/23/2001	HEAT RADIATION FIN USING A CARBON FIBER REINFORCED RESIN AS HEAT RADIATION PLATES STANDING ON A SUBSTRATE	HIGASHI, MITSUTOSHI
09778119	6354480	150	02/05/2001 X	APPARATUS FOR POSITIONING A THIN PLATE	HIGASHI, MITSUTOSHI
09847193	6583383	150	05/02/2001 X	METHOD AND APPARATUS FOR CUTTING A SEMICONDUCTOR WAFER	HIGASHI, MITSUTOSHI
09874277	Not Issued	161	06/06/2001	SEMICONDUCTOR DEVICE HAVING EXTERNAL CONNECTING TERMINALS AND PROCESS FOR MANUFACTURING THE DEVICE	HIGASHI, MITSUTOSHI
09881004	6522719	150	06/14/2001 X	METHOD AND APPARATUS FOR MEASURING A BUMP ON A SUBSTRATE	HIGASHI, MITSUTOSHI
09973111	6538332	150	10/09/2001 X	SEMICONDUCTOR DEVICE AND METHOD OF PRODUCTION OF SAME	HIGASHI, MITSUTOSHI
10013398	6548326	150	12/13/2001 X	SEMICONDUCTOR DEVICE AND PROCESS OF PRODUCING SAME	HIGASHI, MITSUTOSHI
10043943	Not Issued	161	01/11/2002	HEAT RADIATION FIN USING A CARBON FIBER REINFORCED RESIN AS HEAT RADIATION PLATES STANDING ON A SUBSTRATE	HIGASHI, MITSUTOSHI
10083788	6678144	150	02/27/2002 X	CAPACITOR, CIRCUIT BOARD WITH BUILT-IN CAPACITOR AND METHOD FOR PRODUCING THE SAME	HIGASHI, MITSUTOSHI
10114518	Not Issued	161	04/02/2002	SEMICONDUCTOR ELEMENT, CONNECTION STRUCTURE THEREOF, SEMICONDUCTOR DEVICE USING A PLURALITY OF SUCH ELEMENTS AND PROCESSES FOR MAKING THE SAME	HIGASHI, MITSUTOSHI

<u>10162587</u>	<u>6699787</u>	150	06/06/2002 A	SEMICONDUCTOR DEVICE AND METHOD OF PRODUCTION OF SAME	HIGASHI, MITSUTOSHI
<u>10162598</u>	<u>6703310</u>	150	06/06/2002 A	SEMICONDUCTOR DEVICE AND METHOD OF PRODUCTION OF SAME	HIGASHI, MITSUTOSHI
<u>10270823</u>	<u>6797603</u>	150	10/15/2002 A	SEMICONDUCTOR DEVICE AND METHOD OF PRODUCTION OF SAME	HIGASHI, MITSUTOSHI
<u>10335689</u>	<u>6861284</u>	150	01/02/2003 A	SEMICONDUCTOR DEVICE AND PRODUCTION METHOD THEREOF	HIGASHI, MITSUTOSHI
<u>10430652</u>	Not Issued	041	05/06/2003 A	TERMINAL, SEMICONDUCTOR DEVICE, TERMINAL FORMING METHOD AND FLIP CHIP SEMICONDUCTOR DEVICE MANUFACTURING METHOD	HIGASHI, MITSUTOSHI
<u>10453311</u>	Not Issued	092	06/03/2003 A	SUBSTRATE-EMBEDDED CAPACITOR, PRODUCTION METHOD THEREOF, AND CIRCUIT BOARD	HIGASHI, MITSUTOSHI
<u>10645478</u>	Not Issued	092	08/22/2003 A	CAPACITOR, CIRCUIT BOARD, METHOD OF FORMATION OF CAPACITOR, AND METHOD OF PRODUCTION OF CIRCUIT BOARD	HIGASHI, MITSUTOSHI
<u>10704156</u>	Not Issued	041	11/10/2003 A	ELECTRONIC PARTS PACKAGING STRUCTURE AND METHOD OF MANUFACTURING THE SAME	HIGASHI, MITSUTOSHI
<u>10706912</u>	Not Issued	030	11/14/2003 A	ELECTRONIC DEVICES AND ITS PRODUCTION METHODS	HIGASHI, MITSUTOSHI
<u>10708957</u>	Not Issued	071	04/02/2004	PATTERNING APPARATUS AND FILM PATTERNING METHOD	HIGASHI, MITSUTOSHI
<u>10709858</u>	Not Issued	030	06/02/2004 A	ELECTRONIC PARTS PACKAGING STRUCTURE AND METHOD OF MANUFACTURING THE SAME	HIGASHI, MITSUTOSHI
<u>10717591</u>	Not Issued	030	11/21/2003 A	ELECTRONIC PARTS PACKAGING STRUCTURE AND METHOD OF	HIGASHI, MITSUTOSHI

His case

				MANUFACTURING THE SAME	
<u>10720514</u>	Not Issued	092	11/25/2003 X	ELECTRONIC PARTS PACKAGING STRUCTURE HAVING MUTUALLY CONNECTED ELECTRONIC PARTS THAT ARE BURIED IN A INSULATING FILM	HIGASHI, MITSUTOSHI
<u>10744197</u>	Not Issued	041	12/22/2003 A	SUBSTRATE-EMBEDDED CAPACITOR, PRODUCTION METHOD THEREOF, AND CIRCUIT BOARD	HIGASHI, MITSUTOSHI
<u>10756763</u>	Not Issued	030	01/14/2004 A	ELECTRONIC PARTS PACKAGING STRUCTURE AND METHOD OF MANUFACTURING THE SAME	HIGASHI, MITSUTOSHI
<u>10757498</u>	Not Issued	030	01/15/2004 X	METHOD FOR DICING WAFER	HIGASHI, MITSUTOSHI
<u>10771506</u>	Not Issued	041	02/05/2004 X	ELECTRONIC PARTS PACKAGING STRUCTURE AND METHOD OF MANUFACTURING THE SAME	HIGASHI, MITSUTOSHI
<u>10777232</u>	6864120	150	02/12/2004 A	SEMICONDUCTOR DEVICE HAVING A CARBON FIBER REINFORCED RESIN AS A HEAT RADIATION PLATE HAVING A CONCAVE PORTION	HIGASHI, MITSUTOSHI

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Inventor Name Search Result

Your Search was:

Last Name = HIGASHI

First Name = MITSUTOSHI

Application#	Patent#	Status	Date Filed	Title	Inventor Name
<u>10781786</u>	Not Issued	071	02/20/2004 ✓	SEMICONDUCTOR DEVICE HAVING EXTERNAL CONTACT TERMINALS AND METHOD FOR USING THE SAME	HIGASHI, MITSUTOSHI
<u>10795729</u>	Not Issued	030	03/08/2004 X	SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF	HIGASHI, MITSUTOSHI
<u>10796004</u>	Not Issued	020	03/10/2004 ✓	METHOD OF PRODUCTION OF MULTILAYER-CIRCUIT BOARD WITH BUILT-IN SEMICONDUCTOR CHIP	HIGASHI, MITSUTOSHI
<u>10826034</u>	Not Issued	030	04/16/2004 ✓	METHOD FOR MANUFACTURING SEMICONDUCTOR PACKAGE	HIGASHI, MITSUTOSHI
<u>10852063</u>	Not Issued	030	05/24/2004 X	SEMICONDUCTOR DEVICE AND PRODUCTION METHOD THEREOF	HIGASHI, MITSUTOSHI
<u>10904087</u>	Not Issued	030	10/22/2004 ✓	ELECTRONIC PARTS PACKAGING STRUCTURE AND METHOD OF MANUFACTURING THE SAME	HIGASHI, MITSUTOSHI
<u>11011051</u>	Not Issued	020	12/15/2004	PATTERNING APPARATUS AND FILM PATTERNING METHOD	HIGASHI, MITSUTOSHI
<u>11031764</u>	Not Issued	020	01/07/2005 ✓	CAPACITOR, CIRCUIT BOARD WITH BUILT-IN CAPACITOR AND METHOD OF MANUFACTURING THE SAME	HIGASHI, MITSUTOSHI
<u>11031812</u>	Not Issued	020	01/07/2005 ✓	CAPACITOR, CIRCUIT BOARD WITH BUILT-IN	HIGASHI, MITSUTOSHI

			CAPACITOR AND METHOD OF MANUFACTURING THE SAME	
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Inventor Search Completed: No Records to Display.

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Inventor Name Search Result

Your Search was:

Last Name = SAKAGUCHI

First Name = HIDEAKI

Application#	Patent#	Status	Date Filed	Title	Inventor Name
<u>07864668</u>	5473619	150	04/07/1992 X	METHOD AND APPARATUS FOR TESTING A DRIVING CIRCUIT	SAKAGUCHI, HIDEAKI
<u>09358053</u>	6259038	150	07/21/1999 X	SEMICONDUCTOR CHIP MOUNTING BOARD AND METHOD OF INSPECTING THE SAME MOUNTING BOARD	SAKAGUCHI, HIDEAKI
09430189	Not Issued	161 abd	10/29/1999	SEMICONDUCTOR DEVICE HAVING EXTERNAL CONNECTING TERMINALS AND PROCESS FOR MANUFACTURING THE DEVICE	SAKAGUCHI, HIDEAKI
<u>09591785</u>	6420787	150	06/12/2000 X	SEMICONDUCTOR DEVICE AND PROCESS OF PRODUCING SAME	SAKAGUCHI, HIDEAKI
<u>09621586</u>	6535011	150	07/21/2000 J	TESTING DEVICE AND TESTING METHOD FOR A SEMICONDUCTOR INTEGRATED CIRCUIT AND STORAGE MEDIUM HAVING THE TESTING PROGRAM STORED THEREIN	SAKAGUCHI, HIDEAKI
<u>09624014</u>	6766266	150	07/21/2000 X	TESTING DEVICE AND TESTING METHOD FOR SEMICONDUCTOR INTEGRATED CIRCUITS	SAKAGUCHI, HIDEAKI
<u>09627976</u>	6404070	150	07/28/2000	SEMICONDUCTOR DEVICE	SAKAGUCHI, HIDEAKI
09734855	Not Issued	161	12/11/2000	SEMICONDUCTOR DEVICE AND PRODUCTION METHOD THEREOF	SAKAGUCHI, HIDEAKI
<u>09747397</u>	6603202	150	12/22/2000 X	CIRCUIT BOARD-	SAKAGUCHI,

				PROVIDING ARTICLE, CIRCUIT BOARD, SEMICONDUCTOR DEVICE AND PROCESS FOR THE PRODUCTION OF THE SAME	HIDEAKI
<u>09760396</u>	<u>6713863</u>	150	01/12/2001 4	SEMICONDUCTOR DEVICE HAVING A CARBON FIBER REINFORCED RESIN AS A HEAT RADIATION PLATE HAVING A CONCAVE PORTION	SAKAGUCHI, HIDEAKI
09767432	Not Issued	161	01/23/2001	HEAT RADIATION FIN USING A CARBON FIBER REINFORCED RESIN AS HEAT RADIATION PLATES STANDING ON A SUBSTRATE	SAKAGUCHI, HIDEAKI
<u>09847193</u>	<u>6583383</u>	150	05/02/2001 4	METHOD AND APPARATUS FOR CUTTING A SEMICONDUCTOR WAFER	SAKAGUCHI, HIDEAKI
09874277	Not Issued	161	06/06/2001	SEMICONDUCTOR DEVICE HAVING EXTERNAL CONNECTING TERMINALS AND PROCESS FOR MANUFACTURING THE DEVICE	SAKAGUCHI, HIDEAKI
<u>10013398</u>	<u>6548326</u>	150	12/13/2001 4	SEMICONDUCTOR DEVICE AND PROCESS OF PRODUCING SAME	SAKAGUCHI, HIDEAKI
10043943	Not Issued	161	01/11/2002	HEAT RADIATION FIN USING A CARBON FIBER REINFORCED RESIN AS HEAT RADIATION PLATES STANDING ON A SUBSTRATE	SAKAGUCHI, HIDEAKI
<u>10335689</u>	<u>6861284</u>	150	01/02/2003 4	SEMICONDUCTOR DEVICE AND PRODUCTION METHOD THEREOF	SAKAGUCHI, HIDEAKI
<u>10425666</u>	<u>6850085</u>	150	04/30/2003 4	REFERENCE VOLTAGE GENERATING DEVICE, SEMICONDUCTOR INTEGRATED CIRCUIT INCLUDING THE SAME AND TESTING DEVICE AND METHOD FOR SEMICONDUCTOR	SAKAGUCHI, HIDEAKI

				INTEGRATED CIRCUIT	
<u>10430652</u>	Not Issued	041	05/06/2003 X	TERMINAL, SEMICONDUCTOR DEVICE, TERMINAL FORMING METHOD AND FLIP CHIP SEMICONDUCTOR DEVICE MANUFACTURING METHOD	SAKAGUCHI, HIDEAKI
<u>10453311</u>	Not Issued	092	06/03/2003 A	SUBSTRATE-EMBEDDED CAPACITOR, PRODUCTION METHOD THEREOF, AND CIRCUIT BOARD	SAKAGUCHI, HIDEAKI
<u>10617387</u>	6833715	150	07/11/2003	SEMICONDUCTOR TESTING APPARATUS AND SEMICONDUCTOR TESTING METHOD	SAKAGUCHI, HIDEAKI
<u>10708957</u>	Not Issued	071	04/02/2004	PATTERNING APPARATUS AND FILM PATTERNING METHOD	SAKAGUCHI, HIDEAKI
<u>10744197</u>	Not Issued	041	12/22/2003 X	SUBSTRATE-EMBEDDED CAPACITOR, PRODUCTION METHOD THEREOF, AND CIRCUIT BOARD	SAKAGUCHI, HIDEAKI
<u>10757498</u>	Not Issued	030	01/15/2004	METHOD FOR DICING WAFER	SAKAGUCHI, HIDEAKI
<u>10777232</u>	6864120	150	02/12/2004 X	SEMICONDUCTOR DEVICE HAVING A CARBON FIBER REINFORCED RESIN AS A HEAT RADIATION PLATE HAVING A CONCAVE PORTION	SAKAGUCHI, HIDEAKI
<u>10795729</u>	Not Issued	030	03/08/2004 A	SEMICONDUCTOR DEVICE AND MANUFACTURING METHOD THEREOF	SAKAGUCHI, HIDEAKI
<u>10852063</u>	Not Issued	030	05/24/2004 X	SEMICONDUCTOR DEVICE AND PRODUCTION METHOD THEREOF	SAKAGUCHI, HIDEAKI
<u>11011051</u>	Not Issued	020 did not	12/15/2004 X	PATTERNING APPARATUS AND FILM PATTERNING METHOD	SAKAGUCHI, HIDEAKI
<u>11031764</u>	Not Issued	020	01/07/2005 X	CAPACITOR, CIRCUIT BOARD WITH BUILT-IN CAPACITOR AND METHOD OF MANUFACTURING THE SAME	SAKAGUCHI, HIDEAKI
<u>11031812</u>	Not	020	01/07/2005 X	CAPACITOR, CIRCUIT	SAKAGUCHI,

	Issued		BOARD WITH BUILT-IN CAPACITOR AND METHOD OF MANUFACTURING THE SAME	HIDEAKI
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